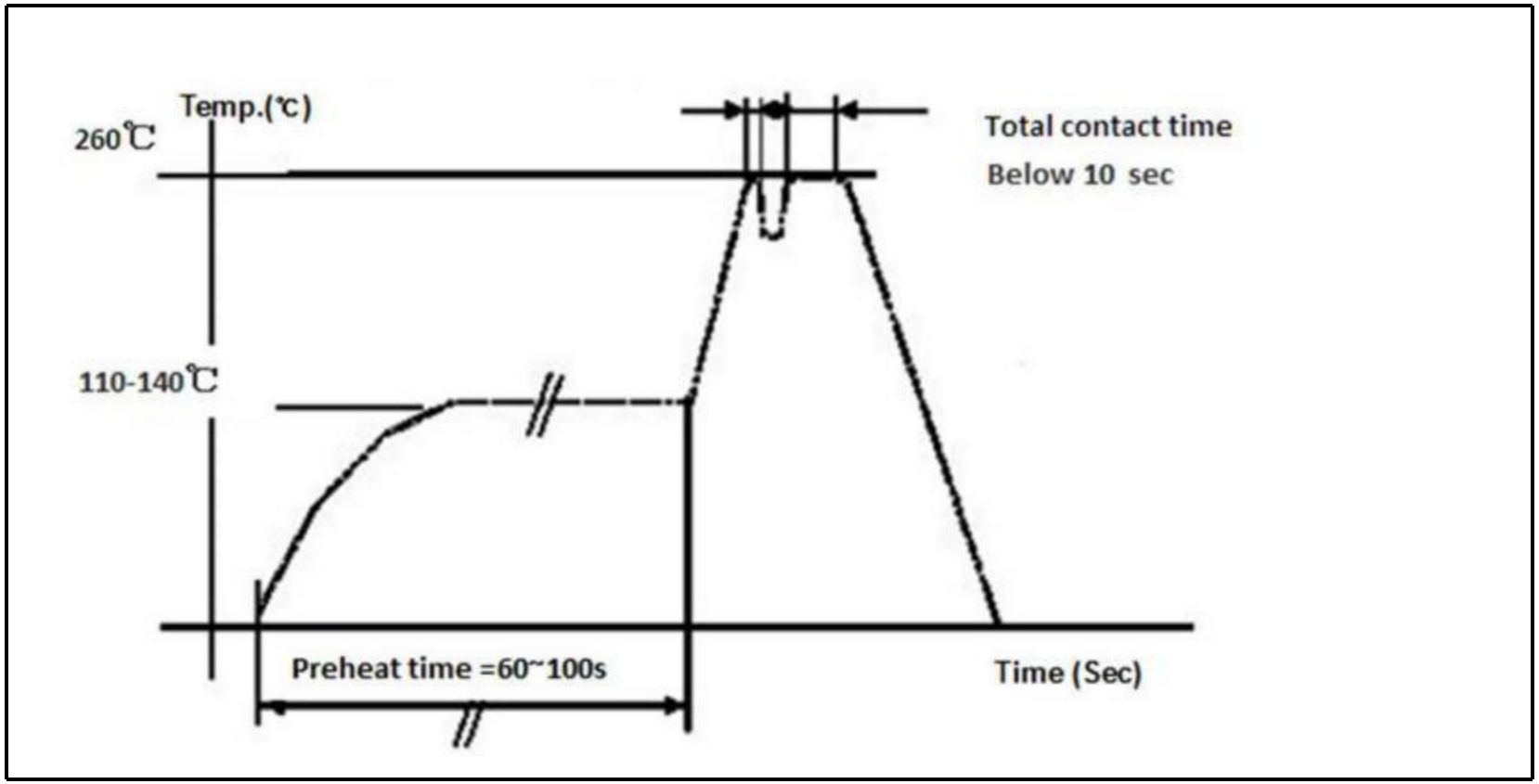
Appendix

Recommended Soldering Profile for Rectifier Diodes (Pb Free)

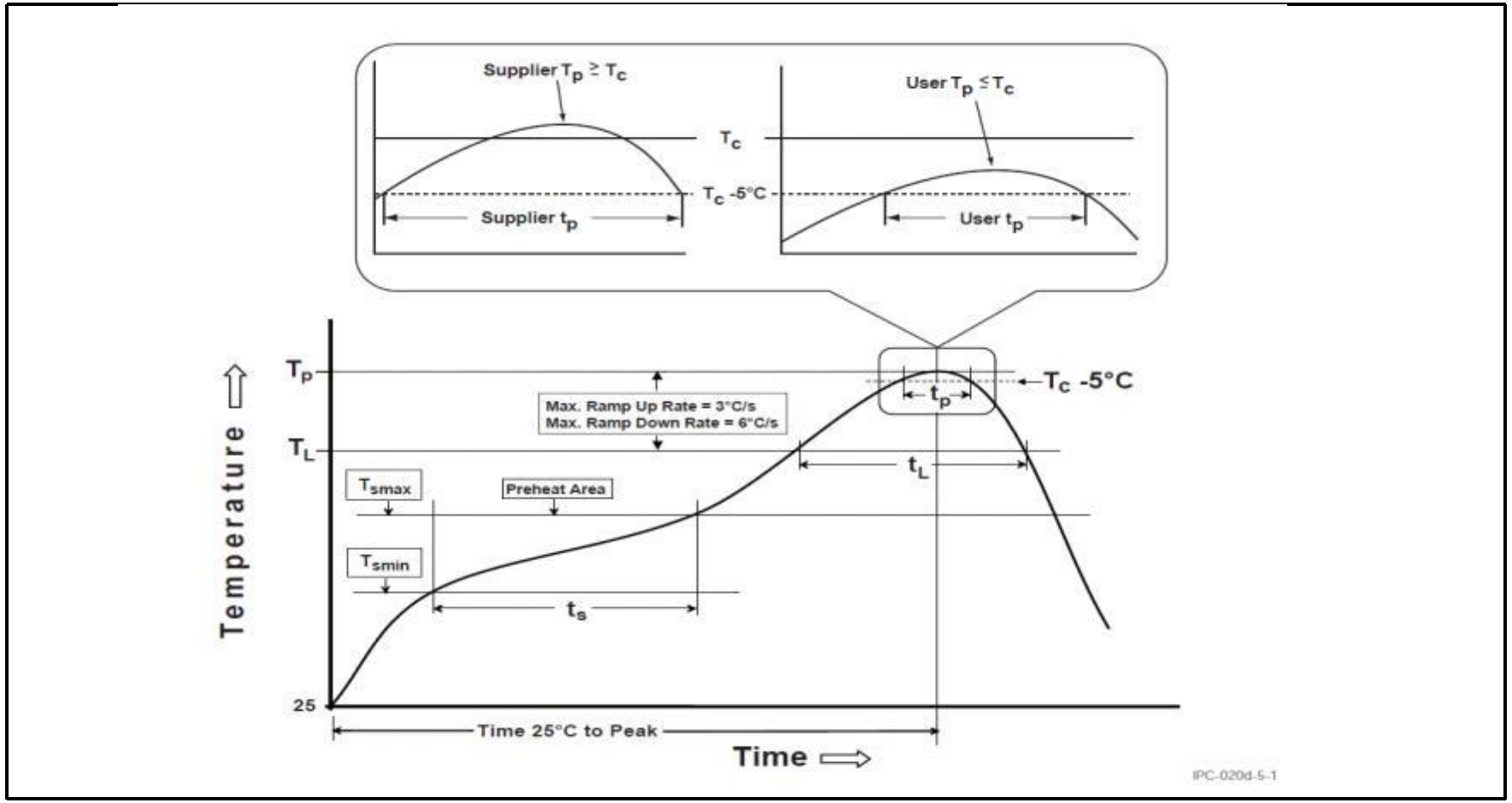
a) Wave Soldering Profile



Appendix

Recommended Soldering Profile for Rectifier Diodes (Pb Free)

b) Reflow Soldering Profile (Pb free Application), refer to IPC/JEDEC J-STD-020



Appendix

Recommended Soldering Profile for Rectifier Diodes (Pb Free)

Preheat/Soak Temperature Min (Tsmin) Temperature Max (Tsmax) Time (ts) from (Tsmin to Tsmax)	**50。C 200。C 60-120 seconds**
Melting Point of Solder (Sn Ag Cu)	217℃
Ramp-up Rate to 217℃(Melting Point of Solder)	3℃/sec
Time at Temp.>217℃ (Melting Point of Solder)	60~150 Sec
Peak Temperature	255±5℃
Time within 5℃below Peak Temp.	20~40 Sec
Cooling Rate	6℃/sec (max)
Time from 25℃ to Peak Temp.	8min (max)